

1009699-034502

1 1. An apparatus for encapsulating a circuit on a
2 circuit board, comprising:

3 a first mold section configured to close on one
4 side of the board, the first mold section having an exposed
5 first conduit;

6 a second mold section configured to close on
7 another side of the board, the second mold section having a
8 second conduit for pushing molding compound into a mold
9 cavity in at least one of the mold sections, the second
10 conduit having a side opened to the first mold section when
11 the first and section mold sections are closed on the board;
12 and

13 a piston slidably mounted inside the first
14 conduit and configured to extend toward the second mold
15 section to close the side of the second conduit.

1 2. The apparatus of claim 1 wherein the board
2 includes a portion that extends over the side of the second
3 conduit, and wherein the piston is configured to crush the
4 portion of the board.

1 3. The apparatus of claim 2 wherein the piston has
2 a face configured to close the side of the second conduit
3 and a rim extending from the face and configured to crush
4 the portion of the board.

1 4. The apparatus of claim 3 wherein the rim is
2 arcuate.

1 5. The apparatus of claim 2 wherein the second
2 mold section has a depression for receiving the board, and
3 wherein the piston has a knife extending from a face and
4 configured to exert force on the board to seat the board
5 against an end stop of the depression when the piston
6 contacts the portion of the board.

1 6. The apparatus of claim 5 wherein the depression
2 has another knife configured to exert force on the board to
3 seat the board in the depression when the piston contacts
4 the portion of the board.

1 7. The apparatus of claim 6 wherein the another
2 knife is asymmetric.

1 8. The apparatus of claim 5 wherein the knife is
2 asymmetric.

1 9. The apparatus of claim 2 wherein the second
2 mold section has a depression for receiving the board, and
3 wherein the depression has a knife extending from the
4 depression and configured to exert force on the board to
5 seat the board in the depression when the piston contacts
6 the portion of the board.

1 10. The apparatus of claim 9 wherein the knife is
2 asymmetric.

1 11. A method for encapsulating a circuit on a
2 circuit board, comprising:
3 closing a first mold section on one side of the
4 board, the first mold section having an exposed first
5 conduit;
6 closing a second mold section on another side
7 of the board, the second mold section having a second
8 conduit for pushing molding compound into a mold cavity in
9 at least one of the mold sections, the second conduit having
10 a side opened to the first mold section when the first and
11 section mold sections are closed on the circuit board; and
12 extending a piston through the first conduit to
13 close the side of the second conduit.

1 12. The method of claim 11, wherein the board
2 partially extends over the side of the second circuit,
3 further comprising:
4 crushing a portion of the board extending over
5 the side of the second conduit.

1 13. The method of claim 11, further comprising:
2 using the piston to exert lateral forces on the
3 board to seat the board within the second mold section.